

CLAIMS

1. A transfer member comprising:
a substrate sheet (2, 52);
a mold release layer (3, 53) of a belt-shaped
5 pattern laminated on the substrate sheet;
an ionizing radiation curing layer (4, 54)
laminated all over a surface on the mold release layer;
a patterned layer (5, 55) laminated all over a
surface or partially on the ionizing radiation curing
10 layer; and
an adhesive layer (6, 56) laminated on the
patterned layer only partially in a portion where the
adhesive layer overlaps with the mold release layer.
2. The transfer member as claimed in claim 1, wherein
15 the adhesive layer is laminated in a region narrower along
a direction of width of the transfer member than a region
where the adhesive layer overlaps with the mold release
layer.
3. The transfer member as claimed in claim 1 or 2,
20 wherein, after being bonded to a resin board (144), the
transfer member has a peel strength smaller than 50 N/m
with respect to the resin board in a portion where the mold
release layer is not provided when the transfer member is
peeled off at an angle of 90° with respect to the resin
25 board.

4. The transfer member as claimed in claim 1 or 2, further comprising: an anchor layer (7, 58) laminated wholly or partially between the ionizing radiation curing layer and the patterned layer.

5. The transfer member as claimed in claim 3, further comprising: an anchor layer (7, 58) laminated wholly or partially between the ionizing radiation curing layer and the patterned layer.

6. The transfer member as claimed in claim 1, wherein the patterned layer is laminated wholly or partially on the ionizing radiation curing layer, the adhesive layer is laminated wholly instead of partially on the patterned layer, and

the transfer member further comprises a nonadhesive layer (57) laminated on the adhesive layer at least partially in a portion where the nonadhesive layer does not overlap with the mold release layer.

7. The transfer member as claimed in claim 3, wherein the patterned layer is laminated wholly or partially on the ionizing radiation curing layer, the adhesive layer is laminated wholly instead of partially on the patterned layer, and

the transfer member further comprises a nonadhesive layer (57) laminated on the adhesive layer at least partially in a portion where the nonadhesive layer

does not overlap with the mold release layer.

8. The transfer member as claimed in claim 4, wherein the patterned layer is laminated wholly or partially on the ionizing radiation curing layer, the adhesive layer is
5 laminated wholly instead of partially on the patterned layer, and

the transfer member further comprises a nonadhesive layer (57) laminated on the adhesive layer at least partially in a portion where the nonadhesive layer
10 does not overlap with the mold release layer.

9. The transfer member as claimed in claim 5, wherein the patterned layer is laminated wholly or partially on the ionizing radiation curing layer, the adhesive layer is laminated wholly instead of partially on the patterned
15 layer, and

the transfer member further comprises a nonadhesive layer (57) laminated on the adhesive layer at least partially in a portion where the nonadhesive layer does not overlap with the mold release layer.